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# SEP 2 0 2005

| CERTIFICATE OF T<br>Applicant(s): Alcoe et al.   | TRANSMISSION BY FACS     | SIMILE (37 CFR 1.8)     | Docket No. END920010135US2 |
|--|--------------------------|-------------------------|----------------------------|
| Application No.  | Filing Date<br>9/18/2003 | Examiner<br>Thao, X. Le | Group Art Unit<br>2814     |
| Invention: THERMALLY ENHANCED LID FOR MULTI-CHIP MODULES   |                          |                         |                            |
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| I hereby certify that this <u>Request for Reconsideration (17 pages with Appendix)</u> (Identify type of correspondence)  is being facsimile transmitted to the United States Patent and Trademark Office (Fax. No. 571-273-8300 |                          |                         |                            |
| on 9/20/2005 (Date)  |                          |                         |                            |
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## SEP 2 0 2005

#### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.: 10/665,669

Applicant(s): Alcoe et al.

Filed.: September 18, 2003

Art Unit: 2814

Dkt. No.: END920010135US2

Examiner: Le, Thao X.

Title: ENHANCED LID FOR MULTI-CHIP MODULES

Honorable Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450

#### REQUEST FOR RECONSIDERATION

This Request for Reconsideration is being filed in response to the Office Action mailed on July 5, 2005. Applicants request this Amendment be entered in the above-identified application and reconsideration of the application in view of the Amendments and Remarks that follow.